

Features

- ◇ Glass passivated chip junction
- ◇ High efficiency, Low VF
- ◇ High current capability
- ◇ High reliability
- ◇ High surge current capability
- ◇ For use in low voltage, high frequency inverter, free wheeling, and polarity protection application.
- ◇ Green compound with suffix "G" on packing code & prefix "G" on datecode

Mechanical Data

- ◇ Case: Molded plastic TS-1
- ◇ Epoxy: UL 94V-0 rate flame retardant
- ◇ Lead: Pure tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- ◇ Polarity: Color band denotes cathode
- ◇ High temperature soldering guaranteed: 260°C/10s / .375", (9.5mm) lead lengths at 5 lbs, (2.3kg) tension
- ◇ Mounting position: Any
- ◇ Weight: 0.20 grams

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	HT 11G	HT 12G	HT 13G	HT 14G	HT 15G	HT 16G	HT 17G	HT 18G	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	300	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	210	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	300	400	600	800	1000	V
Maximum Average Forward Rectified Current .375 (9.5mm) Lead Length @ $T_A=55^\circ\text{C}$	$I_{F(AV)}$	1								A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	30								A
Maximum Instantaneous Forward Voltage (Note 1) @ 1 A	V_F	1.0			1.3		1.7			V
Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Volage @ $T_A=125^\circ\text{C}$	I_R	5 150								uA uA
Maximum Reverse Recovery Time (Note 2)	T_{rr}	50				75				nS
Typical Junction Capacitance (Note 3)	C_j	15				10				pF
Typical Thermal Resistance (Note 4)	$R_{\theta JA}$	95								$^\circ\text{C/W}$
Operating Temperature Range	T_J	- 65 to + 150								$^\circ\text{C}$
Storage Temperature Range	T_{STG}	- 65 to + 150								$^\circ\text{C}$

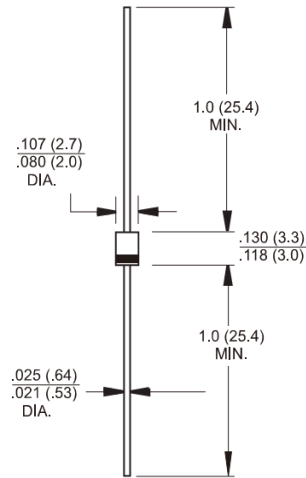
Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

Note 2: Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $IRR=0.25\text{A}$

Note 3: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

Note 4: Mount on Cu-Pad Size 5mm x 5mm on PCB

TS-1



Dimensions in inches and (millimeters)

Marking Diagram



- HT1XG = Specific Device Code
- G = Green Compound
- Y = Year
- M = Work Month

RATINGS AND CHARACTERISTIC CURVES (HT11G THRU HT18G)

FIG. 1- MAXIMUM FORWARD CURRENT DERATING CURVE

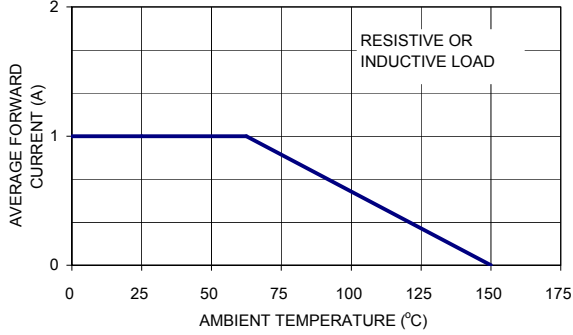


FIG. 2- TYPICAL REVERSE CHARACTERISTICS

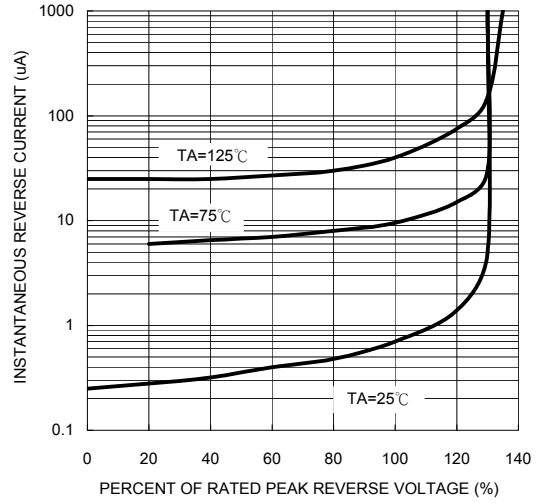


FIG. 3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

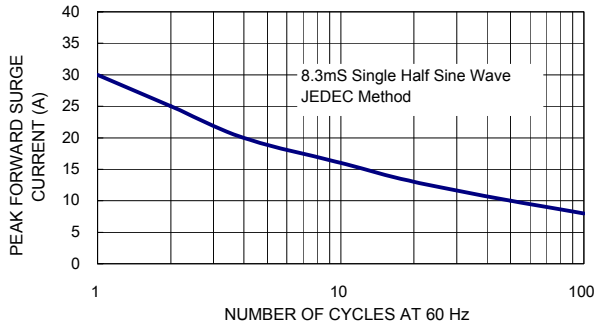


FIG. 5- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

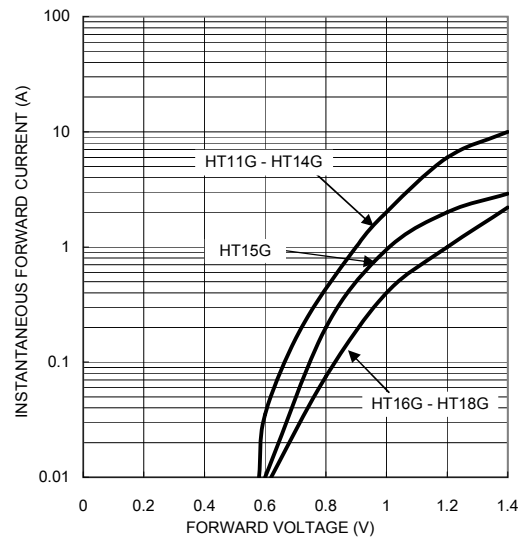


FIG. 4- TYPICAL JUNCTION CAPACITANCE

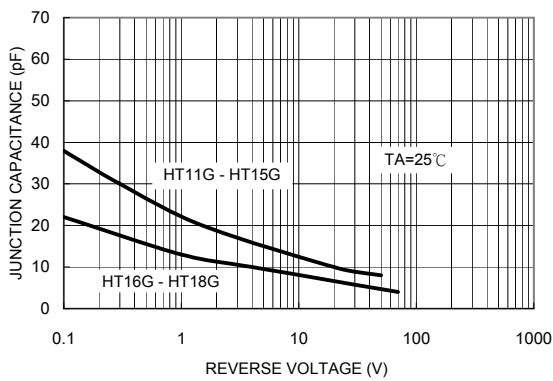


FIG. 6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

